

WHAT IS CLAIMED IS:

1. A multi-layer circuit board, comprising;
a substrate;
5 a first electrical conductive circuit disposed on at least one surface of said substrate;
an resin layer disposed on said first electrical conductive circuit; and
a second electrical conductive circuit disposed on said
10 resin layer;
wherein said resin layer includes a resin compound containing a benzocyclobutene resin, a particulate inorganic filler and an ultraviolet absorbent.
- 15 2. The multi-layer circuit board according to claim 1, wherein the largest particle size of said inorganic filler is not larger than 10 μm .
3. The multi-layer circuit board according to claim 1, wherein
20 average particle size of said inorganic filler is not larger than 2 μm .
4. The multi-layer circuit board according to claim 2, wherein
average particle size of said inorganic filler is not larger
25 than 2 μm .
5. The multi-layer circuit board according to claim 1, wherein

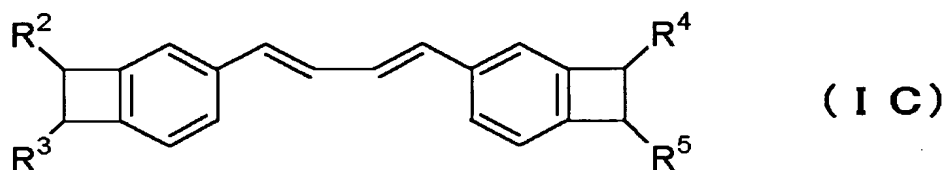
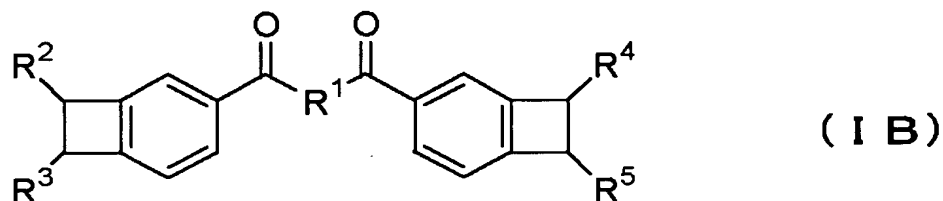
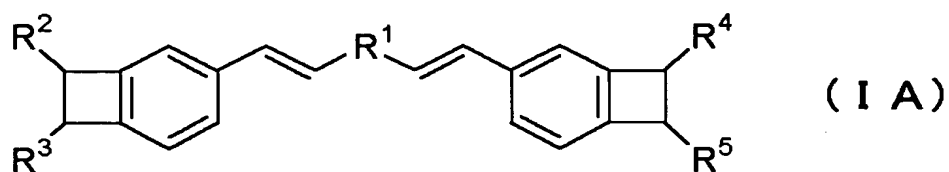
a content of said inorganic filler is in a range from 5 parts by weight to 100 parts by weight relative to 100 parts by weight of said benzocyclobutene resin.

5 6. The multi-layer circuit board according to claim 2, wherein a content of said inorganic filler is in a range from 5 parts by weight to 100 parts by weight relative to 100 parts by weight of said benzocyclobutene resin.

10 7. The multi-layer circuit board according to claim 3, wherein a content of said inorganic filler is in a range from 5 parts by weight to 100 parts by weight relative to 100 parts by weight of said benzocyclobutene resin.

15 8. The multi-layer circuit board according to claim 4, wherein a content of said inorganic filler is in a range from 5 parts by weight to 100 parts by weight relative to 100 parts by weight of said benzocyclobutene resin.

20 9. The multi-layer circuit board according to claim 1, wherein said benzocyclobutene resin is composed by a monomer of a benzocyclobutene derivative having a general formula of IA, IB or IC:



(where R_1 represents: halogen atom; alkyl group; haloalkyl group; aryl group; cycloalkyl group; hydroxyl group; alkoxy group; carboxylic group; alkoxy carbonyl group or acyl group, R_2 , R_3 , R_4 and R_5 , which are same or different, represent: hydrogen atom; halogen atom; alkyl group; haloalkyl group; aryl group; cycloalkyl group; hydroxyl group; alkoxy group; carboxylic group; alkoxy carbonyl group or acyl group, wherein said R_2 and R_3 or said R_4 and R_5 are capable of coupling to form a cyclic structure).

10. The multi-layer circuit board according to claim 1, wherein said ultraviolet absorbent contains benzophenones or benzotriazoles.

11. The multi-layer circuit board according to claim 1, wherein a content of said ultraviolet absorbent is in a range from 0.01 part by weight to 5 parts by weight relative to 100 parts by

weight of the benzocyclobutene resin.

12. The multi-layer circuit board according to claim 1, wherein
the relative dielectric constant of said resin layer is not more
5 than 3.0.

13. The multi-layer circuit board according to claim 1, wherein
the dielectric loss tangent of said resin layer is not more than
0.005.

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14. The multi-layer circuit board according to claim 1, wherein
said resin layer has an ultraviolet absorption region within
a wavelength range from 200 nm to 400 nm.

15 15. A method for manufacturing said multi-layer circuit board
according to claim 1, comprising:

forming a via hole on said resin layer; and

cleaning said via hole by conducting a plasma processing.